

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Pan et al. ✓

Serial No.: 09/998,606 ✓

Filed: 11/30/01 ✓

For: HIGH DENSITY CAPACITOR USING TOPOGRAPHIC SURFACE

Docket No.: TI-31192

Examiner: Nguyen, C.

Art Unit: 2811

#7/B
And
J. Mammella
11/26/02Amendment under 37 CFR 1.115

Assistant Commissioner of Patents

Washington, DC 20231

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TECHNOLOGY CENTER 2800

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 06/26/02. They are respectfully submitted as a full and complete response to that Action.

Please amend the above-referenced application as follows:

In the Claims:

Cancel claims 1-17, claims 11-17 being drawn to a non-elected invention.

Please add the following claims:

- B1
- 18. An integrated circuit having an analog circuit stage, comprising:
a semiconductor layer having a plurality of recesses formed therein;
a dielectric layer over said semiconductor layer including within said plurality of recesses; and

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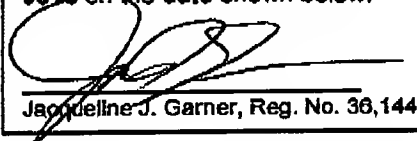
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CERTIFICATION OF FACSIMILE TRANSMISSION

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NAME OF INVENTOR(S): Pan	
TITLE OF INVENTION: High Density Capacitor Using Topographic . . .	
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